■RELIABILITY DATA

1. Operating Temperature Range	
Specified Value	−40～+85℃

2. Storage Temperature Range	
Specified Value	−40～+85℃
Test Methods and Remarks	※with being taped, −20～+40℃

3. Solderability	
Specified Value	At least 75% of immersed terminal surface is covered by new solder.
Test Methods and Remarks	Solder temperature : 240±5℃ Duration : 3±1 sec. Preconditioning : Preheating at 150℃ after immersion into flux.

4. Thermal Shock	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
Test Methods and Remarks	1 hour of recovery after 10 times of 30min.immersion alternately at −40℃ and 85℃ of temperature, followed by evaluating electrical characteristics.

5. High Temperature Storage Test	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
Test Methods and Remarks	1 hour of recovery under standard condition after 96 hours recovery with 85℃ of temperature, followed by evaluating electrical characteristics.

6. Low Temperature Storage Test	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
Test Methods and Remarks	1 hour of recovery under standard condition after 96 hours recovery with −40℃ of temperature, followed by evaluating electrical characteristics.

7. Humidity Storage Test	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
Test Methods and Remarks	1 hour of recovery under standard condition after 96 hours recovery with 60℃ of temperature, 90～95% relative humidity followed by evaluating electrical characteristics.

8. Resistance to Reflow	
Specified Value	Shall satisfy required VSWR value of individual specifications for each item.
Test Methods and Remarks	Two times of reflow soldering by recommended profile attached, followed by evaluating electrical characteristics.